

74ALVC162838

Low Voltage 16-Bit Selectable Register/Buffer with 3.6V Tolerant Inputs/Outputs and 26Ω Series Resistors in the Outputs

General Description

The ALVC162838 contains sixteen non-inverting selectable buffered or registered paths. The device can be configured to operate in a registered, or flow through buffer mode by utilizing the register enable (REGE) and Clock (CLK) signals. The device operates in a 16-bit word wide mode. All outputs can be placed into 3-State through the use of the OE pin. These devices are ideally suited for buffered or registered 168 pin and 200 pin SDRAM DIMM memory modules.

The 74ALVC162838 is designed for low voltage (1.65V to 3.6V) V_{CC} applications with I/O compatibility up to 3.6V. The ALVC162838 is also designed with 26Ω series resistors in the outputs. This design reduces line noise in applications such as memory address drivers, clock drivers, and bus transceivers/transmitters.

The 74ALVC162838 is fabricated with an advanced CMOS technology to achieve high speed operation while maintaining low CMOS power dissipation.

Features

- Compatible with PC100 and PC133 DIMM module specifications
- 1.65V–3.6V V_{CC} supply operation
- 3.6V tolerant inputs and outputs
- 26Ω series resistors in the outputs
- t_{PD} (CLK to O_n)
 - 4.4 ns max for 3.0V to 3.6V V_{CC}
 - 5.9 ns max for 2.3V to 2.7V V_{CC}
 - 9.8 ns max for 1.65V to 1.95V V_{CC}
- Power-off high impedance inputs and outputs
- Supports live insertion and withdrawal (Note 1)
- Uses patented noise/EMI reduction circuitry
- Latchup conforms to JEDEC JED78
- ESD performance:
 - Human body model > 2000V
 - Machine model > 200V

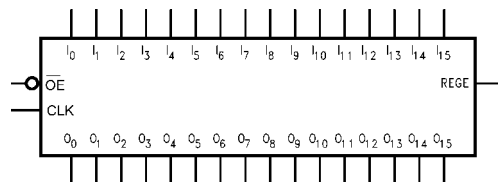
Note 1: To ensure the high-impedance state during power up or power down, OE should be tied to V_{CC} through a pull-up resistor. The minimum value of the resistor is determined by the current -sourcing capability of the driver.

Ordering Code:

Ordering Code	Package Number	Package Descriptions
74ALVC162838T	MTD48	48-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 6.1mm Wide

Devices also available in Tape and Reel. Specify by appending suffix letter "X" to the ordering code.

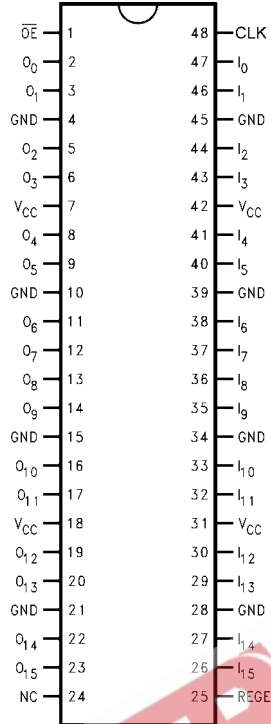
Logic Symbol



Pin Descriptions

Pin Names	Description
\overline{OE}	Output Enable Input (Active LOW)
I_0 – I_{15}	Inputs
O_0 – O_{15}	Outputs
CLK	Clock Input
REGE	Register Enable Input

Connection Diagram



Truth Table

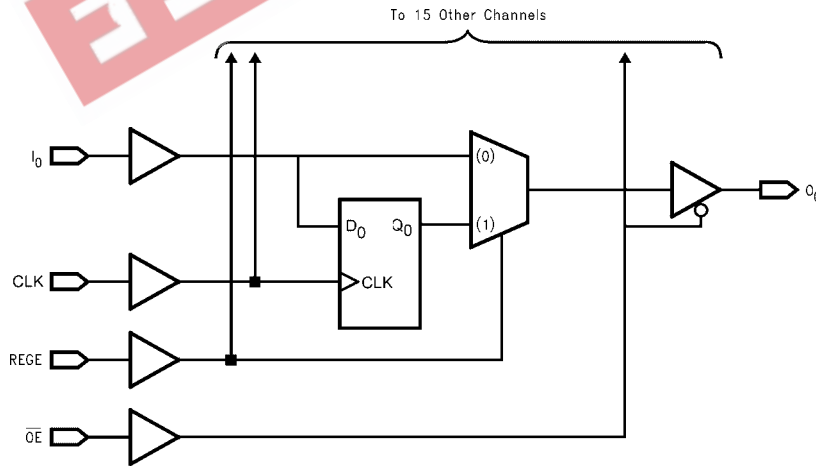
Inputs				Outputs
CLK	REGE	I _n	OE	O _n
↑	H	H	L	H
↑	H	L	L	L
X	L	H	L	H
X	L	L	L	L
X	X	X	H	Z

H = Logic HIGH
 L = Logic LOW
 X = Don't Care, but not floating
 Z = High Impedance
 ↑ = LOW-to-HIGH Clock Transition

Functional Description

The 74ALVC162838 consists of sixteen selectable non-inverting buffers or registers with word wide modes. Mode functionality is selected through operation of the CLK and REGE pin as shown by the truth table. When REGE is held at a logic HIGH, the device operates as a 16-bit register. Data is transferred from I_n to O_n on the rising edge of the CLK input. When the REGE pin is held at a logic LOW the device operates in a flow through mode and data propagates directly from the I to the O outputs. All outputs can be 3-stated by holding the OE pin at a logic HIGH.

Logic Diagram



Absolute Maximum Ratings (Note 2)		Recommended Operating Conditions (Note 4)	
Supply Voltage (V_{CC})	-0.5V to +4.6V	Power Supply	1.65V to 3.6V
DC Input Voltage (V_I)	-0.5V to 4.6V	Operating	0V to V_{CC}
Output Voltage (V_O) (Note 3)	-0.5V to $V_{CC} + 0.5V$	Input Voltage	0V to V_{CC}
DC Input Diode Current (I_{IK})		Output Voltage (V_O)	0V to V_{CC}
$V_I < 0V$	-50 mA	Free Air Operating Temperature (T_A)	-40°C to +85°C
DC Output Diode Current (I_{OK})		Minimum Input Edge Rate ($\Delta t/\Delta V$)	
$V_O < 0V$	-50 mA	$V_{IN} = 0.8V$ to $2.0V$, $V_{CC} = 3.0V$	10 ns/V
DC Output Source/Sink Current (I_{OH}/I_{OL})	± 50 mA	Note 2: The Absolute Maximum Ratings are those values beyond which the safety of the device cannot be guaranteed. The device should not be operated at these limits. The parametric values defined in the Electrical Characteristics tables are not guaranteed at the Absolute Maximum Ratings. The "Recommended Operating Conditions" table will define the conditions for actual device operation.	
DC V_{CC} or GND Current per Supply Pin (I_{CC} or GND)	± 100 mA	Note 3: I_O Absolute Maximum Rating must be observed.	
Storage Temperature Range (T_{STG})	-65°C to +150°C	Note 4: Floating or unused control inputs must be held HIGH or LOW.	

DC Electrical Characteristics

Symbol	Parameter	Conditions	V_{CC} (V)	Min	Max	Units
V_{IH}	HIGH Level Input Voltage		1.65 - 1.95	$0.65 \times V_{CC}$		V
			2.3 - 2.7	1.7		
			2.7 - 3.6	2.0		
V_{IL}	LOW Level Input Voltage		1.65 - 1.95		$0.35 \times V_{CC}$	V
			2.3 - 2.7		0.7	
			2.7 - 3.6		0.8	
V_{OH}	HIGH Level Output Voltage	$I_{OH} = -100 \mu A$	1.65 - 3.6	$V_{CC} - 0.2$		V
		$I_{OH} = -2$ mA	1.65	1.2		
		$I_{OH} = -4$ mA	2.3	1.9		
		$I_{OH} = -6$ mA	2.3	1.7		
		$I_{OH} = -8$ mA	3.0	2.4		
		$I_{OH} = -12$ mA	2.7	2		
V_{OL}	LOW Level Output Voltage	$I_{OL} = 100 \mu A$	1.65 - 3.6		0.2	V
		$I_{OL} = 2$ mA	1.65		0.45	
		$I_{OL} = 4$ mA	2.3		0.4	
		$I_{OL} = 6$ mA	2.3		0.55	
		$I_{OL} = 8$ mA	3.0		0.55	
		$I_{OL} = 12$ mA	2.7		0.6	
I_I	Input Leakage Current	$0 \leq V_I \leq 3.6V$	1.65 - 3.6		± 5.0	μA
I_{OZ}	3-STATE Output Leakage	$0 \leq V_O \leq 3.6V$, $V_I = V_{IH}$ or V_{IL}	1.65 - 3.6		± 10	μA
I_{OFF}	Power Off Leakage Current	$0V \leq (V_I, V_O) \leq 3.6V$	0		10	mA
I_{CC}	Quiescent Supply Current	$V_I = V_{CC}$ or GND, $I_O = 0$	3.6		40	μA
ΔI_{CC}	Increase in I_{CC} per Input	$V_{IH} = V_{CC} - 0.6V$	2.7 - 3.6		750	μA

AC Electrical Characteristics										
Symbol	Parameter	$T_A = -40^\circ\text{C to } +85^\circ\text{C}, R_L = 500\Omega$								Units
		$C_L = 50\text{ pF}$				$C_L = 30\text{ pF}$				
		$V_{CC} = 3.3V \pm 0.3V$		$V_{CC} = 2.7V$		$V_{CC} = 2.5 \pm 0.2V$		$V_{CC} = 1.8V \pm 0.15V$		
		Min	Max	Min	Max	Min	Max	Min	Max	
f_{MAX}	Maximum Clock Frequency	250		200		200		100		MHz
t_{PHL}, t_{PLH}	Propagation Delay Bus-to-Bus (REGE = 0)	1.3	4.0	1.5	5.4	1.0	4.9	1.5	9.8	ns
t_{PHL}, t_{PLH}	Propagation Delay Clock to Bus (REGE = 1)	1.3	4.4	1.5	5.9	1.0	5.4	1.5	9.8	ns
t_{PHL}, t_{PLH}	Propagation Delay REGE to Bus	1.3	4.4	1.5	5.9	1.0	5.4	1.5	9.8	ns
t_{PZL}, t_{PZH}	Output Enable Time	1.3	4.5	1.5	6.2	1.0	5.7	1.5	9.8	ns
t_{PLZ}, t_{PHZ}	Output Disable Time	1.3	4.6	1.5	5.1	1.0	4.6	1.5	8.3	ns
t_S	Setup Time	1.0		1.0		1.0		2.5		ns
t_H	Hold Time	0.7		0.7		0.7		1.0		ns
t_W	Pulse Width	1.5		1.5		1.5		4.0		ns
Capacitance										
Symbol	Parameter	Conditions	$T_A = +25^\circ\text{C}$		Units					
			V_{CC}	Typical						
C_{IN}	Input Capacitance	$V_I = 0V$ or V_{CC}	3.3	6	pF					
C_{OUT}	Output Capacitance	$V_I = 0V$ or V_{CC}	3.3	7	pF					
C_{PD}	Power Dissipation Capacitance	Outputs Enabled	$f = 10\text{ MHz}, C_L = 0\text{ pF}$	3.3	20	pF				
				2.5	20					

AC Loading and Waveforms

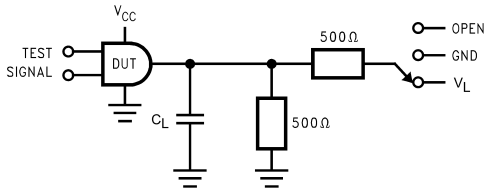


FIGURE 1. AC Test Circuit

TABLE 1. Values for Figure 1

TEST	SWITCH
t_{PLH} , t_{PHL}	Open
t_{PZL} , t_{PLZ}	V_L
t_{PZH} , t_{PHZ}	GND

TABLE 2. Variable Matrix
(Input Characteristics: $f = 1\text{MHz}$; $t_r = t_f = 2\text{ns}$; $Z_0 = 50\Omega$)

Symbol	V_{CC}			
	$3.3\text{V} \pm 0.3\text{V}$	2.7V	$2.5\text{V} \pm 0.2\text{V}$	$1.8\text{V} \pm 0.15\text{V}$
V_{mi}	1.5V	1.5V	$V_{CC}/2$	$V_{CC}/2$
V_{mo}	1.5V	1.5V	$V_{CC}/2$	$V_{CC}/2$
V_X	$V_{OL} + 0.3\text{V}$	$V_{OL} + 0.3\text{V}$	$V_{OL} + 0.15\text{V}$	$V_{OL} + 0.15\text{V}$
V_Y	$V_{OH} - 0.3\text{V}$	$V_{OH} - 0.3\text{V}$	$V_{OH} - 0.15\text{V}$	$V_{OH} - 0.15\text{V}$
V_L	6V	6V	$V_{CC} * 2$	$V_{CC} * 2$

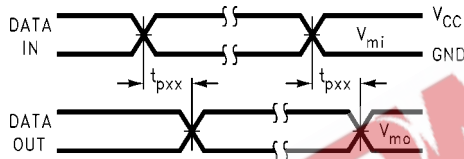


FIGURE 2. Waveform for Inverting and Non-Inverting Functions

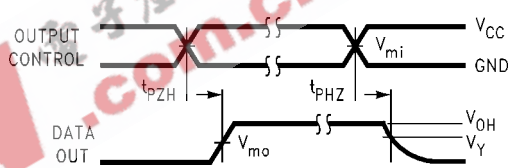


FIGURE 3. 3-STATE Output High Enable and Disable Times for Low Voltage Logic

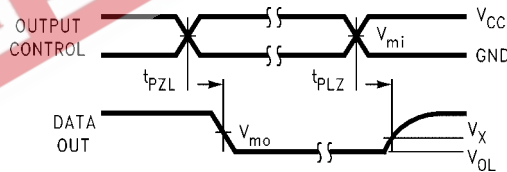


FIGURE 4. 3-STATE Output Low Enable and Disable Times for Low Voltage Logic

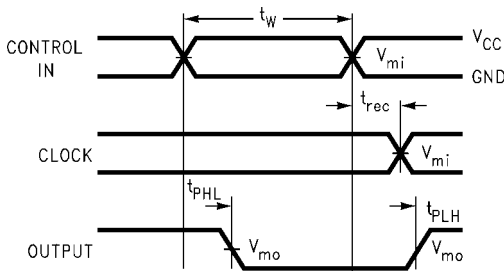


FIGURE 5. Propagation Delay, Pulse Width and t_{rec} Waveforms

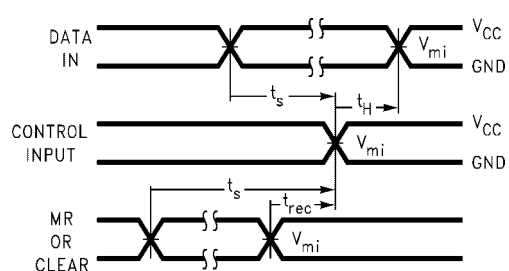


FIGURE 6. Setup Time, Hold Time and Recovery Time for Low Voltage Logic

Physical Dimensions

inches (millimeters) unless otherwise noted

Symbol	Dimension	Value
A	Lead Width	0.1
B	Lead Height	0.2
C	Lead Thickness	0.1
D	Lead Spacing	0.27
E	Lead Pitch	0.50
F	Lead Height	0.90
G	Lead Height	1.2
H	Lead Thickness	0.13
I	Lead Spacing	0.15
J	Lead Spacing	0.10
K	Lead Spacing	0.10
L	Lead Spacing	0.10
M	Lead Spacing	0.10
N	Lead Spacing	0.10
O	Lead Spacing	0.10
P	Lead Spacing	0.10
Q	Lead Spacing	0.10
R	Lead Spacing	0.10
S	Lead Spacing	0.10
T	Lead Spacing	0.10
U	Lead Spacing	0.10
V	Lead Spacing	0.10
W	Lead Spacing	0.10
X	Lead Spacing	0.10
Y	Lead Spacing	0.10
Z	Lead Spacing	0.10

NOTES:

- CONFORMS TO JEDEC REGISTRATION MO-153, VARIATION AB, REF NOTE 6, DATE 7/93.
- DIMENSIONS ARE IN MILLIMETERS.
- DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- DIMENSIONS AND TOLERANCES PER ANSI Y14.5M, 1982.

MTD48RevB1

48-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 6.1mm Wide Package Number MTD48

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